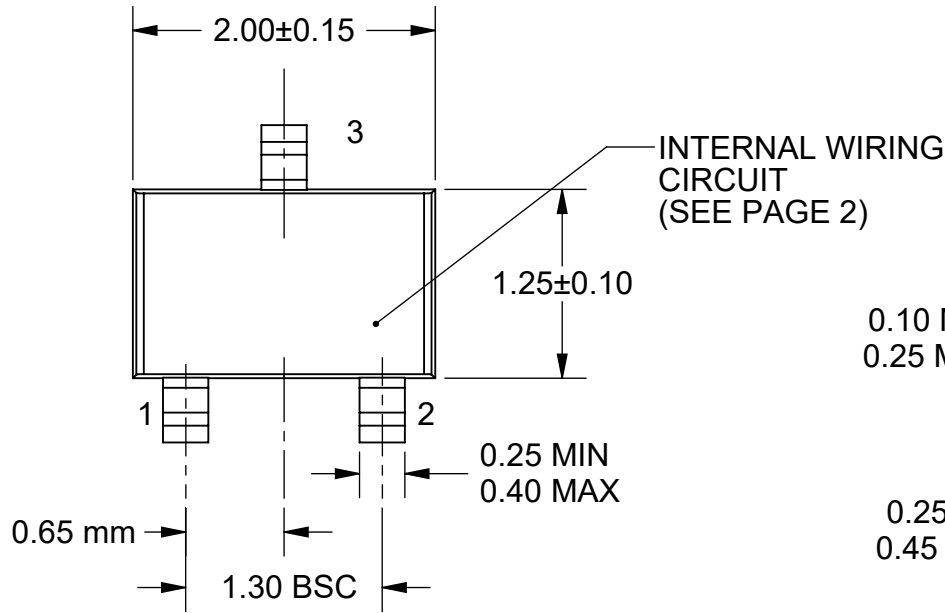
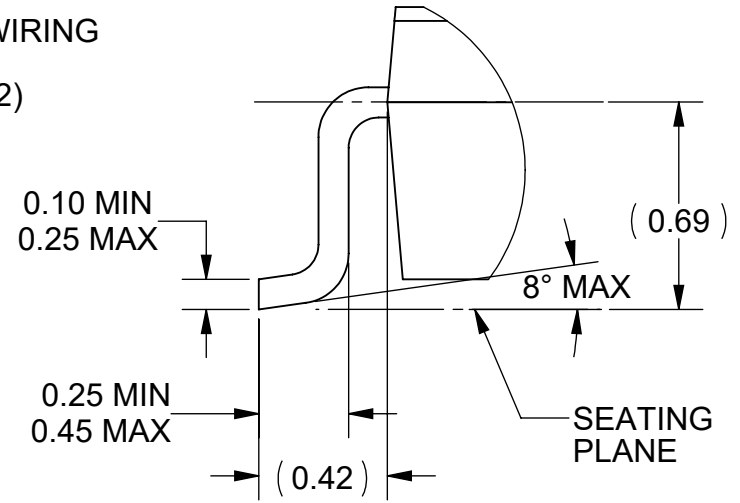


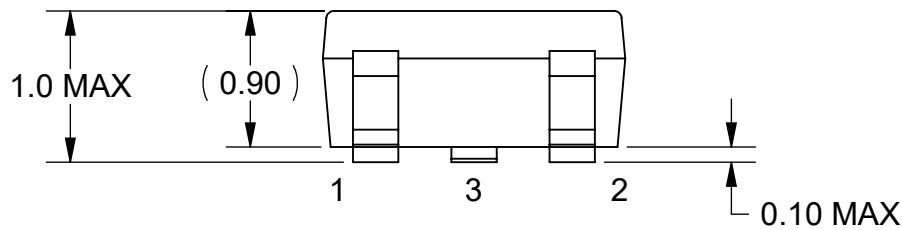
TOP VIEW



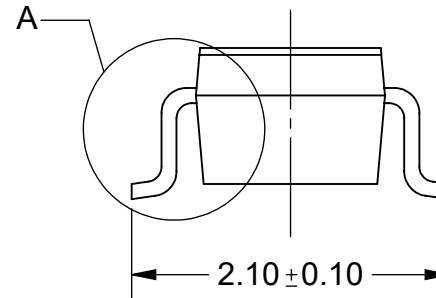
DETAIL A
SCALE 40 : 1



SIDE VIEW



END VIEW

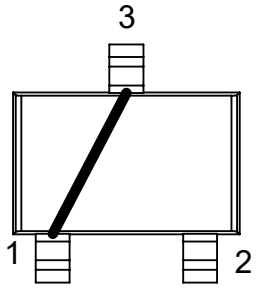


Notes: (Unless Otherwise Specified).

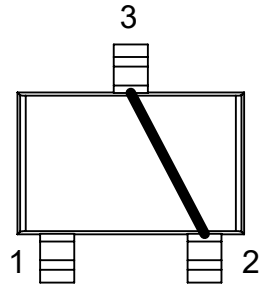
- 1) DIMENSIONS IN mm.
- 2) SEE JUMPER DIAGRAMS (PAGE 2).
- 3) SEE PART NUMBER CONFIGURATION (PAGE 4).
- 4) RECOMMENDED PC BOARD LAYOUT PATTERN (PAGE 7).

APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	12/26/2019				
ENG M. Hart	12/26/2019	TITLE SOT323 ZERO OHM JUMPER			
MFG		SCALE 20:1	SIZE A	DRAWING NO.	REV
QA				120323	A
CUST		DO NOT SCALE DRAWING		SHEET 1 OF 8	
REVISED					

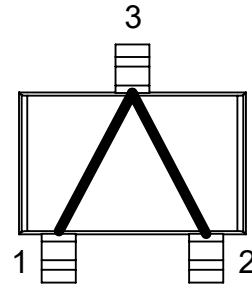
INTERNAL WIRING CIRCUIT (JUMPER)
DAISY CHAIN PART NUMBER SUFFIX
TOP VIEW



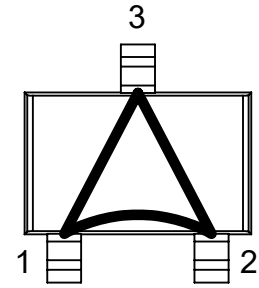
DC13
1-WIRE



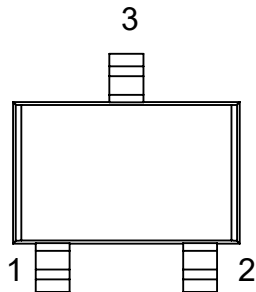
DC23
1-WIRE



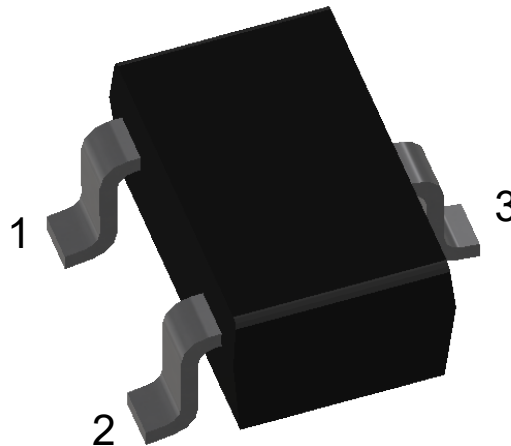
DC123
2-WIRE



DC1231
3-WIRE
SAFETY WIRE
DESIGN

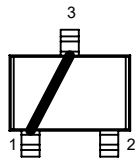


-ISO
NO WIRES
FULLY ISOLATED

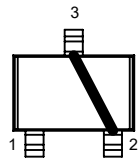
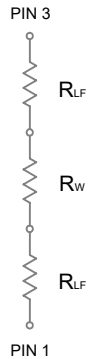


TopLine [®]			
TITLE		SOT323 ZERO OHM JUMPER	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	120323	A
DO NOT SCALE DRAWING			SHEET 2 OF 8

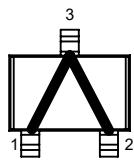
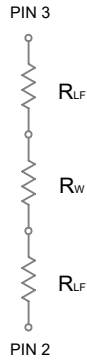
SCHEMATIC EQUIVALENT INTERNAL CIRCUIT



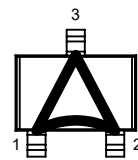
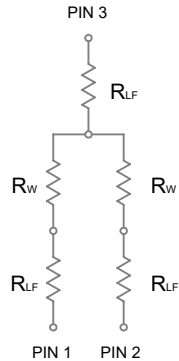
DC13
1-WIRE



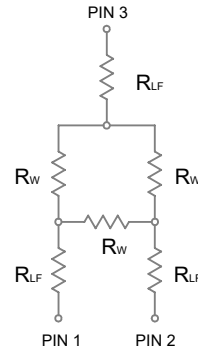
DC23
1-WIRE



DC123
2-WIRE



DC1231
3-WIRE
SAFETY WIRE



R_W = WIRE-BOND.
 R_{LF} = LEAD FRAME.

TEMPERATURE RATING	
JUNCTION TEMP T_J	150 °C
STORAGE TEMP T_{stg}	-65 °C TO 150 °C
OPERATING TEMP	-65 °C TO 150 °C
PEAK REFLOW TEMP T_{reflow} 10 SECONDS	260 °C

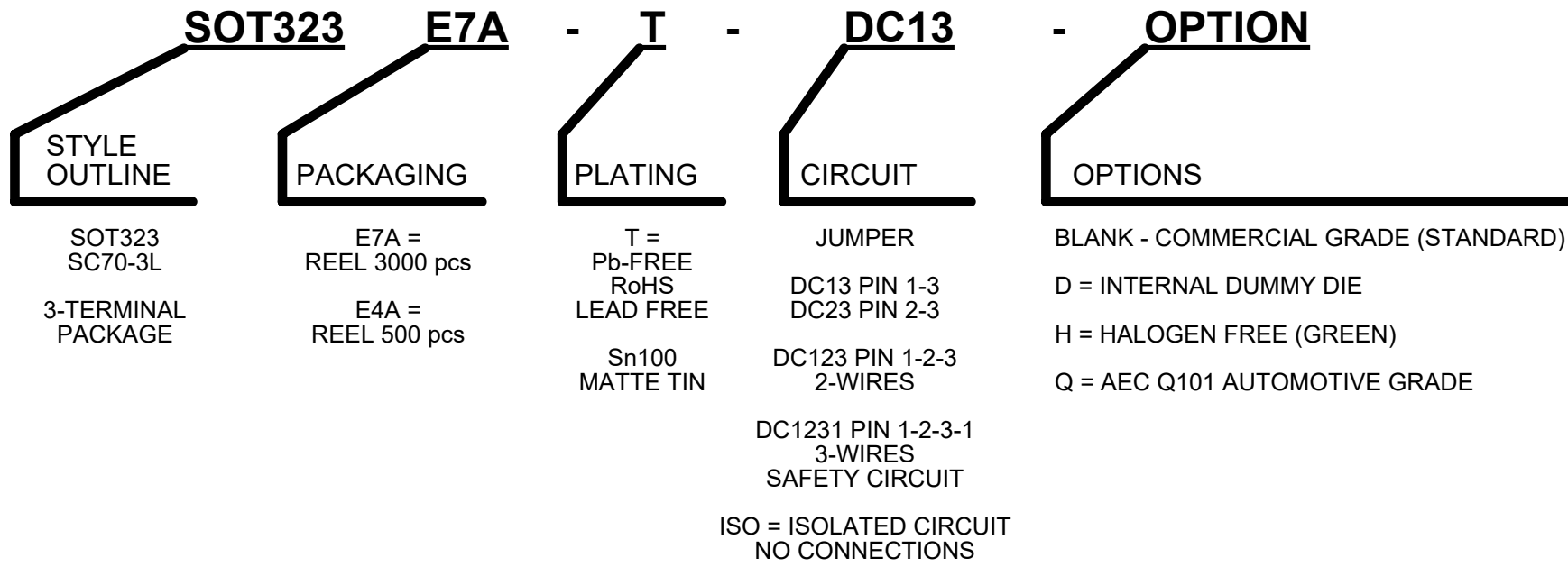
MAXIMUM ELECTRICAL (DC) RATING	
WORKING VOLTAGE	75 V
CURRENT RATING	100 mA
POWER @ 25 °C	350 mW

THERMAL RESISTANCE	
JUNCTION TO AMBIENT ($T_a=25^\circ$) $R_{th(j-a)}$	350K/W

ELECTRICAL RESISTANCE MILIOHM (DC) MAX			
CIRCUIT	PIN 1 TO 3	PIN 2 TO 3	PIN 1 TO 2
DC13	50 mΩ	--	--
DC23	--	50 mΩ	--
DC123	50 mΩ	50 mΩ	75 mΩ
DC1231	50 mΩ	50 mΩ	50 mΩ

TopLine ®			
TITLE SOT323 ZERO OHM JUMPER			
SCALE 8:1	SIZE A	DRAWING NO. 120323	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 8

PART NUMBERING SYSTEM



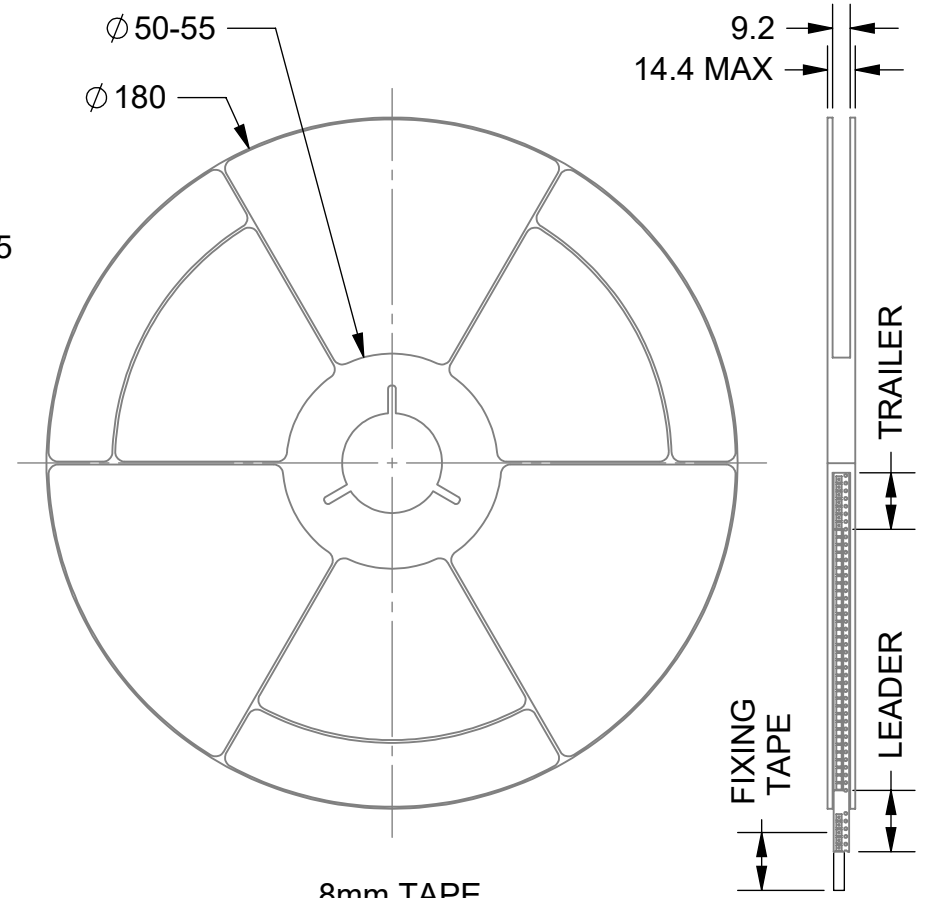
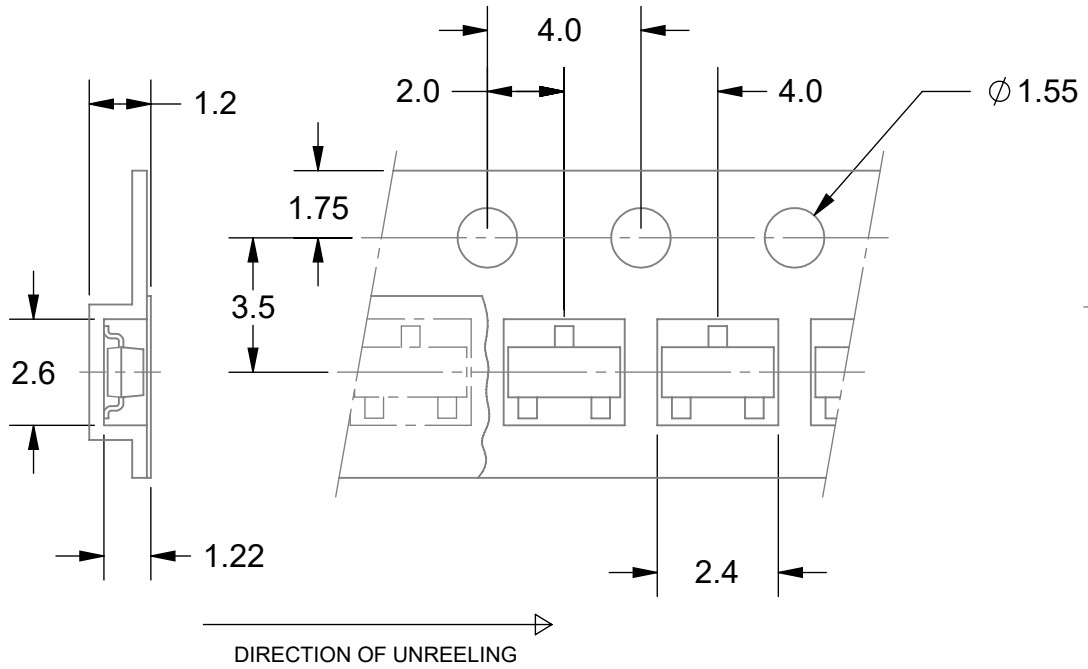
PART NUMBER	SHORTED PINS	NOTES	RoHS Pb-FREE	MSL LEVEL	HALOGEN FREE	GRADE	TOP MARK
SOT323E7A-TIN	N/A	DUMMY	YES	3	NO	COMMERCIAL	N/A
SOT323E7A-T-ISO	NONE	FULLY ISOLATED	YES	3	NO	COMMERCIAL	ISO
SOT323E7A-T-DC13D	1-3	1-WIRE	YES	3	NO	COMMERCIAL	D13
SOT323E7A-T-DC23D	2-3	1-WIRE	YES	3	NO	COMMERCIAL	D23
SOT323E7A-T-DC123	1-2-3	2-WIRES	YES	3	NO	COMMERCIAL	123
SOT323E7A-T-DC123D	1-2-3	2-WIRES	YES	3	NO	COMMERCIAL	123
SOT323E7A-T-DC13H	1-3	1-WIRE	YES	1	YES	COMMERCIAL	13H
SOT323E7A-T-DC13Q	1-3	1-WIRE	YES	1	YES	AEC-Q101	13Q
SOT323E7A-T-DC23H	2-3	1-WIRE	YES	1	YES	COMMERCIAL	23H
SOT323E7A-T-DC23Q	2-3	1-WIRE	YES	1	YES	AEC-Q101	23Q
SOT323E7A-T-DC1231H	1-2-3	3-WIRES	YES	1	YES	COMMERCIAL	3H
SOT323E7A-T-DC1231Q	1-2-3	3-WIRES	YES	1	YES	AEC-Q101	3Q

NOTES: ADD "D" TO END OF PART NUMBER FOR DUMMY SILICON DIE.

TopLine ®			
TITLE SOT323 ZERO OHM JUMPER			
SCALE 25:1	SIZE A	DRAWING NO. 120323	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 8

TAPE SPECIFICATION FOR SOT-323
SURFACE MOUNT DEVICE

SOT-323 PACKAGE REEL



8mm TAPE
SIZE OF REEL
180mm (7")
3,000 PCS

ALL DIMENSIONS IN mm

TopLine [®]			
TITLE SOT323 ZERO OHM JUMPER			
SCALE 1:1	SIZE A	DRAWING NO. 120323	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 8	

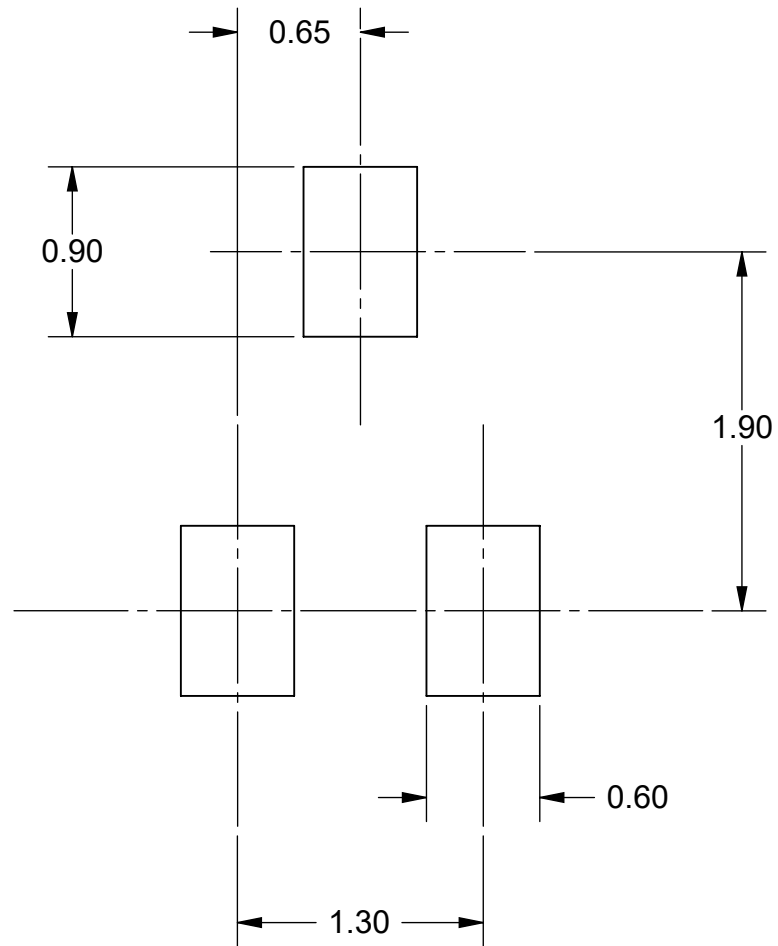
MATERIALS CONTENT DECLARATION FORM

SOT323 PACKAGE

1 PC WT: 5.47mg					
COMPOSITION BREAKDOWN	M.U.M (MAKE UP OF MATERIALS)	CHEMICAL COMPOSITION	CAS NO	CONTENT (%TOTAL = 100%)	SUBSTANCE WEIGHT (mg)
LEADFRAME (1.3mg)	ALLOY-42	IRON (Fe) NICKEL (Ni) SILVER (Ag)	7439-89-6 7440-02-0 7440-22-4	13.71% 9.51% 0.55%	0.75 mg 0.52 mg 0.03 mg
CHIP (0.23 mg)	SILICON	SILICON (Si)	7440-21-3	4.20 %	0.23 mg
BONDING WIRE (0.02 mg)	GOLD or COPPER	GOLD (Au) COPPER (Cu)	7440-57-5 7440-50-8	0.37 %	0.02 mg
ENCAPSULATION (3.69 mg)	EPOXY RESIN	SILICON DIOXIDE (SiO2) EPOXY Phenol Resin Metal Hydroxide	60676-86-0 29690-82-2 ---	51.94 % 6.75 % 6.54 % 2.22 %	2.841 mg 0.369 mg 0.358 mg 0.122 mg
TERMINATION PLATING (0.23 mg)	MATTE TIN	TIN (Sn)	7440-31-5	4.20 %	0.23 mg

TopLine [®]			
TITLE SOT323 JUMPER ZERO OHM JUMPER			
SCALE 1:1	SIZE A	DRAWING NO. 120323	REV A
DO NOT SCALE DRAWING			SHEET 6 OF 8

PC BOARD LAND PATTERN



Notes: (Unless Otherwise Specified).

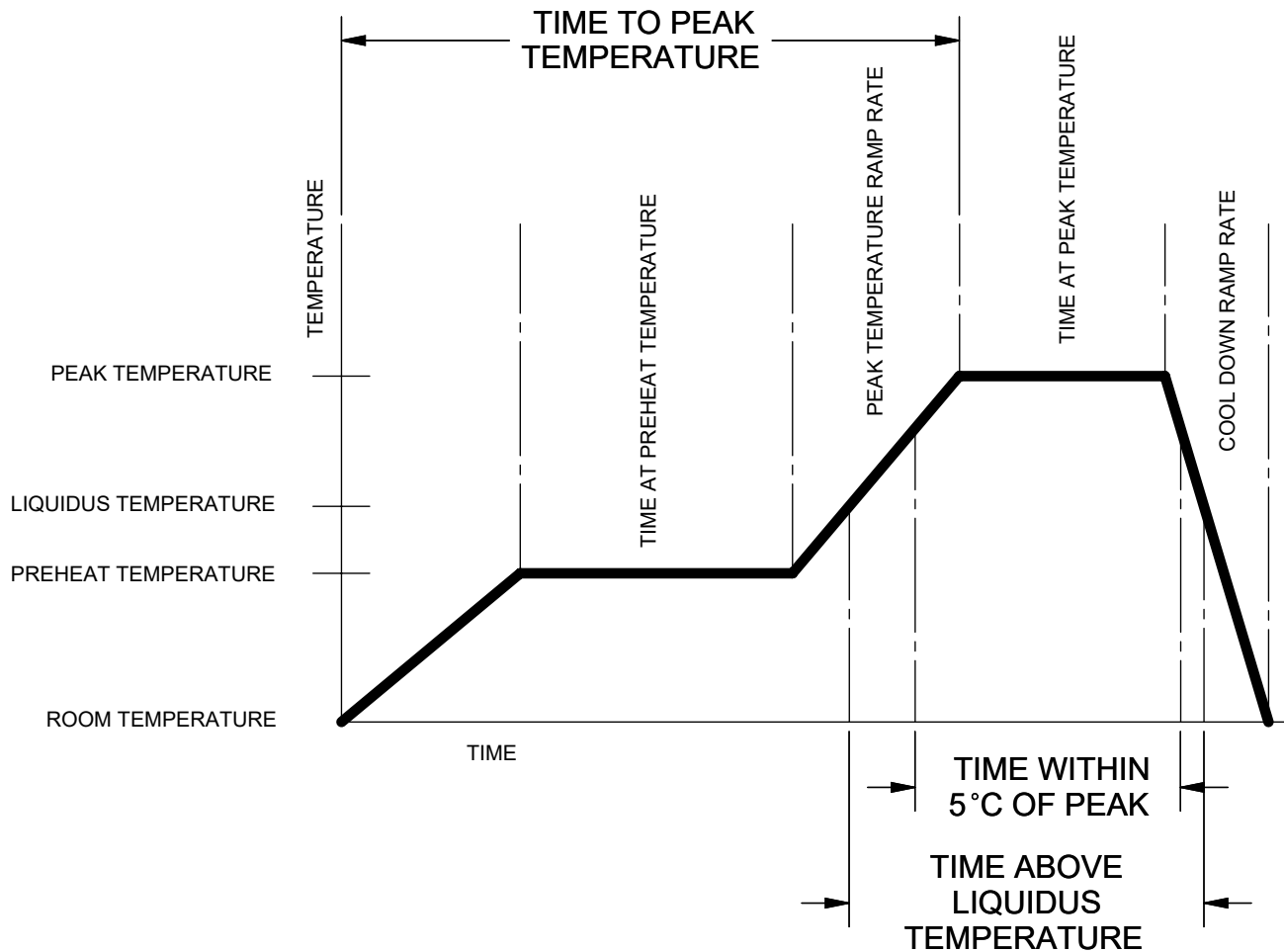
1) DIMENSIONS IN mm.

2) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine[®]

TITLE		SOT323 ZERO OHM JUMPER	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	120323	A
DO NOT SCALE DRAWING			SHEET 7 OF 8

LEAD FREE REFLOW PROFILE OF SMD PACKAGE



DESCRIPTION	REQUIREMENT
AVERAGE PREHEAT RAMP RATE	3°C /SECOND MAXIMUM
PREHEAT TEMPERATURE	150°C MINIMUM, 200°C MAXIMUM
PREHEAT TIME	60 TO 80 SECONDS
RAMP TO PEAK	3°C /SECOND MAXIMUM
TIME OVER LIQUIDUS (217°C)	60 TO 150 SECONDS
PEAK TEMPERATURE	260°C +0/-5°C
TIME WITHING 5°C OF PEAK	20 TO 40 SECONDS
RAMP - COOL DOWN	6°C /SECONDS MAXIMUM
TIME 25°C TO PEAK	8 MINUTES MAXIMUM

TopLine ®			
TITLE		SOT323 ZERO OHM JUMPER	
SCALE	SIZE	DRAWING NO.	REV
1:1	A	120323	A
DO NOT SCALE DRAWING			SHEET 8 OF 8